

**Features:**

- Isolated mounting base 2500V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

**Typical Applications**

- Inverter
- Inductive heating
- Chopper

V <sub>RSM</sub>	V <sub>RRM</sub>	Type & Outline
700V	600V	MZx75-06-216F3
900V	800V	MZx75-08-216F3
1100V	1000V	MZx75-10-216F3
1300V	1200V	MZx75-12-216F3
1500V	1400V	MZx75-14-216F3
1700V	1600V	MZx75-16-216F3
1900V	1800V	MZx75-18-216F3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T <sub>J</sub> (°C)	VALUE			UNIT
				Min	Type	Max	
I <sub>F(AV)</sub>	Mean forward current	180° half sine wave 50Hz Single side cooled, T <sub>C</sub> =100°C	140			75	A
I <sub>F(RMS)</sub>	RMS forward current					118	A
I <sub>RRM</sub>	Repetitive peak current	at V <sub>RRM</sub>	140			20	mA
I <sub>FSM</sub>	Surge forward current	10ms half sine wave V <sub>R</sub> =0.6V <sub>RRM</sub>	140			2.0	kA
I <sup>2</sup> t	I <sup>2</sup> t for fusing coordination					20	A <sup>2</sup> s*10 <sup>3</sup>
V <sub>FO</sub>	Threshold voltage		140			0.80	V
r <sub>F</sub>	Forward slope resistance					4.25	mΩ
V <sub>FM</sub>	Peak forward voltage	I <sub>FM</sub> =225A	25			2.00	V
t <sub>rr</sub>	Reverse recovery time	I <sub>FM</sub> =75A, t <sub>p</sub> =1000μs, -di/dt=20A/μs, V <sub>R</sub> =50V	140		1.5		μs
R <sub>th(j-c)</sub>	Thermal resistance Junction to case	Single side cooled per chip				0.310	°C /W
R <sub>th(c-h)</sub>	Thermal resistance case to heatsink	Single side cooled per chip				0.080	°C /W
F <sub>m</sub>	Terminal connection torque(M6)				6.0		N·m
	Mounting torque(M6)				6.0		N·m
V <sub>iso</sub>	Isolation voltage	50Hz, R.M.S, t=1min, I <sub>iso</sub> : 1mA(MAX)		2500			V
T <sub>vj</sub>	Junction temperature			-40		140	°C
T <sub>stg</sub>	Stored temperature			-40		125	°C
W <sub>t</sub>	Weight				320		g
Outline	216F3						

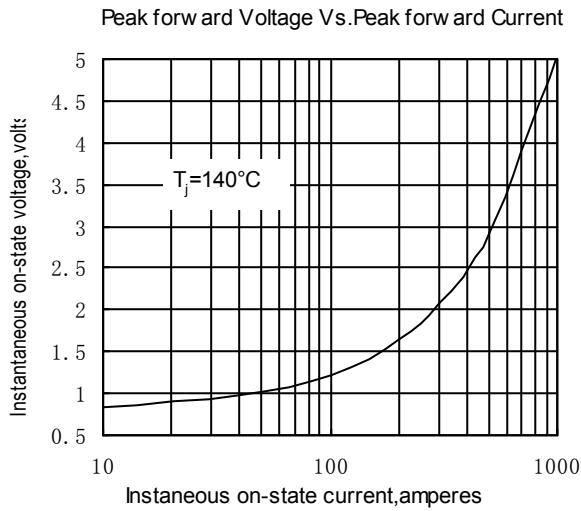


Fig.1

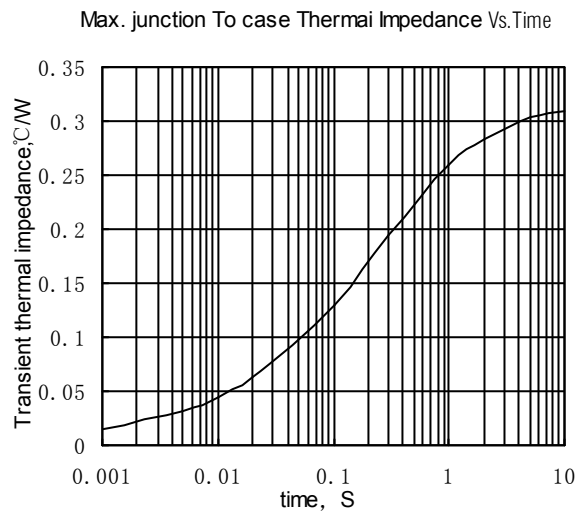


Fig.2

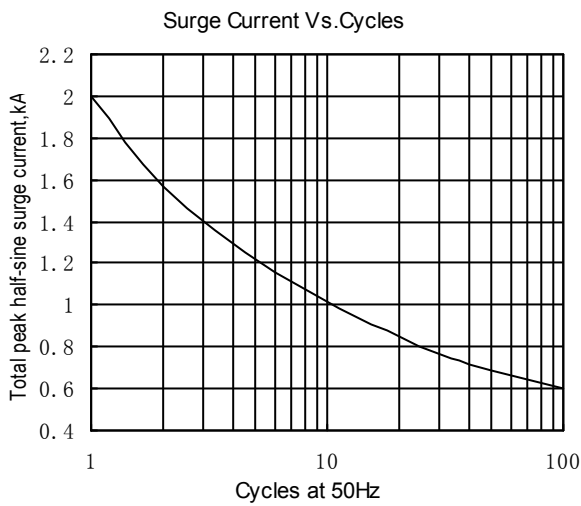


Fig.3

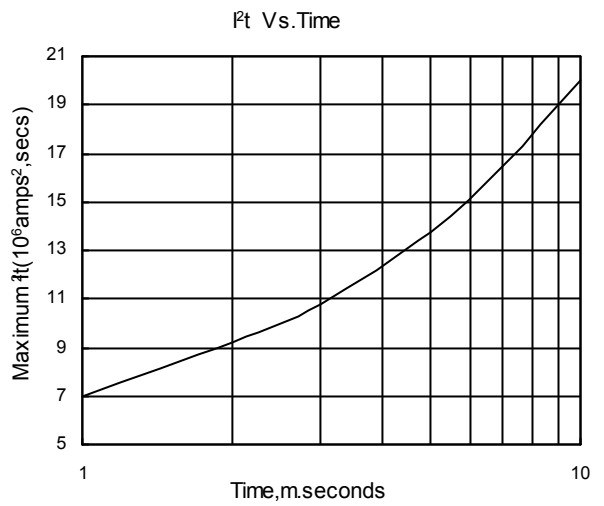


Fig.4

Outline:

